L Number	Hits	Search Text	DB	Time stamp
1	113	257/777 and (semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/12 19:05
2	142	361/760 and (semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/12 19:11
3	175	(438/108 or 438/109) and (semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/12 19:11
−	920	(pad) with (top or upper) near surface with (semiconductor or die or chip) same (pad) with (bottom or lower) near surface with (semiconductor or die or chip)	USPAT	2004/05/11 14:22
−	1	"4127321".PN.	USPAT	2004/05/11 14:11
−	1	"4796977".PN.	USPAT	2004/05/11 14:11
−	1	"4867543".PN.	USPAT	2004/05/11 14:12
−	1	"5073010".PN.	USPAT	2004/05/11 14:12
−	1	"5130830".PN.	USPAT	2004/05/11 14:12
−	1	"5221989".PN.	USPAT	2004/05/11 14:12
−	1	"5381307".PN.	USPAT	2004/05/11 14:12
−	6	"5497258"	USPAT	2004/05/11 14:21
−	125	(pad) with both near surface with (semiconductor or die or chip)	USPAT	2004/05/11 14:33
−	0	"20030205814"	USPAT	2004/05/11 14:34
−	1	"20030205814"	USPAT; US-PGPUB	2004/05/11 14:42
−	1	"6559584"	USPAT; US-PGPUB	2004/05/11 14:39
−	3	"6559548"	USPAT; US-PGPUB	2004/05/11 14:39
−	1	"20030205814" and material with (first or second)	USPAT; US-PGPUB	2004/05/11 14:59
−	1	"5939789".PN.	USPAT	2004/05/11 14:50
−	1	"6211569".PN.	USPAT	2004/05/11 14:56
−	1	"6452274".PN.	USPAT	2004/05/11 14:57
−	1	"6534870".PN.	USPAT	2004/05/11 14:58
−	1	"6559548".PN.	USPAT	2004/05/11 14:58
−	57	"5539652"	USPAT; US-PGPUB	2004/05/11 15:56
−	12709	(semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue)	USPAT; US-PGPUB	2004/05/12 15:22
−	6041	(semiconductor or die or chip or IC) and (flow$4) with (adhesive or glue)	USPAT; US-PGPUB	2004/05/11 16:19
−	1605	(semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)	USPAT; US-PGPUB	2004/05/11 16:20
−	1208	(semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)	USPAT	2004/05/12 13:23
−	3	((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (semiconductor or die or chip or IC) with small with (flow$4) near (adhesive or glue)	USPAT	2004/05/11 16:23
−	0	((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (semiconductor or die or chip or IC) with gab with (flow$4) near (adhesive or glue)	USPAT	2004/05/11 16:23
−	9	((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (semiconductor or die or chip or IC) with gap with (flow$4) near (adhesive or glue)	USPAT	2004/05/11 16:24

—	27	((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (semiconductor or die or chip or IC) with (gap or space) with (flow$4) near (adhesive or glue)	USPAT	2004/05/11 16:30
—	1	((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (semiconductor or die or chip or IC) with (dam) with (flow$4) near (adhesive or glue)	USPAT	2004/05/11 16:31
—	46	((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (semiconductor or die or chip or IC) same (dam or gap or spac$3) with (flow$4) near (adhesive or glue)	USPAT	2004/05/11 16:37
—	193	((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (dam or gap or spac$3) with (flow$4) near (adhesive or glue)	USPAT	2004/05/11 16:38
—	147	(((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (dam or gap or spac$3) with (flow$4) near (adhesive or glue)) not (((semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)) and (semiconductor or die or chip or IC) same (dam or gap or spac$3) with (flow$4) near (adhesive or glue))	USPAT	2004/05/11 16:38
—	0	"20020094608"	USPAT	2004/05/11 16:44
—	1	"20020094608"	USPAT; US-PGPUB	2004/05/11 16:44
—	10	438/118 and flowable near adhesive	USPAT	2004/05/11 16:45
—	1	5422435.pn. and adhesive with epoxy	USPAT	2004/05/12 12:07
—	1208	(semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue)	USPAT	2004/05/12 15:21
—	10	(semiconductor or die or chip or IC) and (flow$4) near (adhesive or glue) same (underfill$3 or under near fill$3 or under-fill)	USPAT	2004/05/12 15:22
—	51	(semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue) same (underfill$3 or under near fill$3 or under-fill)	USPAT	2004/05/12 15:28
—	324	(semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue) same (encapsulat$3 or mold$3 near resin)	USPAT	2004/05/12 15:28
—	196	((semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue) same (encapsulat$3 or mold$3 near resin)) and wir$3	USPAT	2004/05/12 15:49
—	128	((semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue) same (encapsulat$3 or mold$3 near resin)) not (((semiconductor or die or chip or IC) and (flow$4 or injet$3 or drop$4 or insert$3) with (adhesive or glue) same (encapsulat$3 or mold$3 near resin)) and wir$3)	USPAT	2004/05/12 15:49
—	12	"5663530"	USPAT	2004/05/12 16:09
—	1		USPAT	2004/05/12 16:05
—	1		USPAT	2004/05/12 16:05
—	1		USPAT	2004/05/12 16:05
—	1		USPAT	2004/05/12 16:05
—	1		USPAT	2004/05/12 16:06
—	1		USPAT	2004/05/12 16:06
—	1		USPAT	2004/05/12 16:06
—	1		USPAT	2004/05/12 16:07
—	1		USPAT	2004/05/12 16:07
—	1		USPAT	2004/05/12 16:07
—	1		USPAT	2004/05/12 16:07
—	1		USPAT	2004/05/12 16:07

-	1			USPAT	2004/05/12 16:07
-	40	"5376588"		USPAT	2004/05/12 18:58
-	1			USPAT	2004/05/12 16:12
-	1			USPAT	2004/05/12 16:12
-	1			USPAT	2004/05/12 16:12
-	1			USPAT	2004/05/12 16:12
-	1			USPAT	2004/05/12 16:12